

FEATURES

- Leadfree Compatible FR4 Laminates & Prepregs
- Tg: 180°C (DSC)
- High Heat Resistance
- Low Z-Axis CTE
- Excellent Through Hole Reliability
- Superior CAF Performance
- Low Water Absorption
- UL 94 V-0 Flame Rating

APPLICATIONS

- Servers
- Storage Area Networks (SANs)
- Switches & Routers
- High Layer Count PCBs
- Computers
- Medical
- Test

PRODUCT CONTACTS

BRYAN WONG

Director of NA Sales
 Email: Bryan.wong@paramount-usa.com
 Phone: 847- 274-5746

BARRY O'REILLY

Director of NA Sales
 Email:boreilly@midlanticpa.com
 Phone:610-212-3158

Web: www.shengyi-usa.com

GENERAL PROPERTIES

	PROPERTY	TYPICAL VALUE	UNIT	CONDITION	TEST METHOD
Thermal	Glass Transition Temperature, Tg	185	°C	A	DMA IPC-TM-650 2.4.24.2
		180	°C	A	DSC IPC-TM650 2.4.25
	Thermal Expansion, Z CTE	45	ppm/°C	A	Before Tg, IPC-TM-650 2.4.41
		220	ppm/°C	A	After Tg, IPC-TM-650 2.4.41
	Decomposition Temperature, Td	345	°C	A	TMA IPC-TM650 2.4.24.6
	Delamination Time, T260	60	minutes	A	TMA IPC-TM650 2.4.24
	Delamination Time, T288	20	minutes	A	TMA IPC-TM650 2.4.24
	Delamination Time, T300	5	minutes	A	TMA IPC-TM650 2.4.24
Electrical	Dielectric Constant (Dk)	4.80	-	1 MHz	IPC-TM-650 2.5.5.9
	Dissipation Factor (Df)	0.013	-	1 MHz	IPC-TM-650 2.5.5.9
	Volume Resistivity	2.20E+08	MΩ·cm	After moisture resistance	IPC-TM-650 2.5.17.1
	Surface Resistivity	7.90E+07	MΩ	After moisture resistance	IPC-TM-650 2.5.17.1
	Dielectric Breakdown	45+NB	kV	D-48/50+D-0.5/23	IPC-TM-650 2.5.6
Physical	Thermal Conductivity	0.62	W/m·K	100°C	ASTM D5470
	Water Absorption	0.10	%	D-24/23	IPC-TM-650 2.6.2.1
	Copper Peel Strength	1.38 (7.9)	N/mm (lb/in.)	after solder float 1 oz. EDC Foil	IPC-TM-650 2.4.8
	Flammability	94V-0	-	A	UL

PRODUCT SPECIFICATION

THICKNESS	COPPER FOIL	STANDARD SIZE
0.002"-0.125" (0.5mm to 3.2mm)	3/8 oz. - 3oz. (12um - 105um)	40" x 48" (1020mm x 1220mm)
0.002"-0.125" (0.5mm to 3.2mm)	3/8 oz. - 3oz. (12um - 105um)	42" x 48" (1070mm x 1220mm)
0.002"-0.125" (0.5mm to 3.2mm)	3/8 oz. - 3oz. (12um - 105um)	36" x 48" (915mm x 1220mm)

⁽¹⁾ Typical values are a representation of an average value for the population of the property. For specification values contact SYTECH Corporation. The information in this data sheet is intended to assist you in designing with SYTECH's circuit materials. It is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose or that any results shown in this data sheet will be achieved by a user for a particular purpose. The user is responsible for determining the suitability of SYTECH's circuit materials for each application.